



## Novel Thermal and Nonthermal Food Processing Technologies

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### Message from the Guest Editor

Preserving or altering the eating quality of food by heating still remains the most important method of food processing. However, heat can destroy food components that are responsible for flavor, taste, color, or texture. Non-thermal food processing technologies have the same objectives as novel thermal technologies. Since non-thermal food processing technologies generate little heat during processing, more fresh-like products can be obtained.

The aim of this Special Issue is to show the potential applications of novel thermal and non-thermal processing technologies in food processing. We invite authors to submit innovative research papers or comprehensive review papers discussing these novel thermal treatment and non-thermal food processing technologies. Papers that address the combination of thermal- and non-thermal technologies are also welcome.

Prof. Dong-Un Lee

*Guest Editor*

### Keywords

- novel thermal processing
- non-thermal processing
- emerging technology
- ohmic heating
- radio frequency heating
- high hydrostatic pressure
- pulsed electric field
- cold plasma





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## Message from the Editor-in-Chief

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